

| Layer Name | Gerber Document | Copper Thickness | Dielectric Height | Dielectric Material | Dielectric Type |
|--------------------|-----------------|------------------|-------------------|---------------------|-----------------|
| Top Solder Mask | (.GTS) | | 0.4mil | | Solder Resist |
| Top Layer | (.GTL) | 2.8mil | 19mil | FR-4 | Core |
| MidLayer1 | (.G1) | 2.8mil | 18.4mil | FR-4 | PrePreg |
| MidLayer2 | (.G2) | 2.8mil | 19mil | FR-4 | Core |
| Bottom Layer | (.GBL) | 2.8mil | | | |
| Bottom Solder Mask | (.GBS) | | 0.4mil | | Solder Resist |

| DESIGN INFORMATION | |
|---|---|
| BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION) | |
| 3000MIL | X 3000MIL |
| Number of Layers : | 4 |
| MIN. TRACK WIDTH: | 8 MIL |
| MIN. CLEARANCE: | 8 MIL |
| MIN. VIA PAD SIZE: | 22 MIL |
| MINIMUM ANNULAR RING PER | 0.05mm (2MIL) EXTERNAL IPC-D-275 CLASS 2 LEVEL C |
| REGISTRATION TOLERANCES: | METAL +/- 5 MIL HOLES +/- 3 MIL |

MATERIAL:

FR-4 FR-4 High Tg OTHER _____

THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____

TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

COPPER THICKNESS (FINISHED):

OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)

INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz)

DRILLING:

REFERENCE: AS SHOWN NC_DRILL FILES

PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:

SILKSCREEN: TOP BOTTOM

SILKSCREEN COLOR: WHITE OTHER _____

SOLDER RESIST COLOR: GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG) Pb-FREE HASL
 OTHER _____

ARRAY/PANEL: CUT AND TRM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

ANSI IPC-A-600F CLASS -> 1 2 3

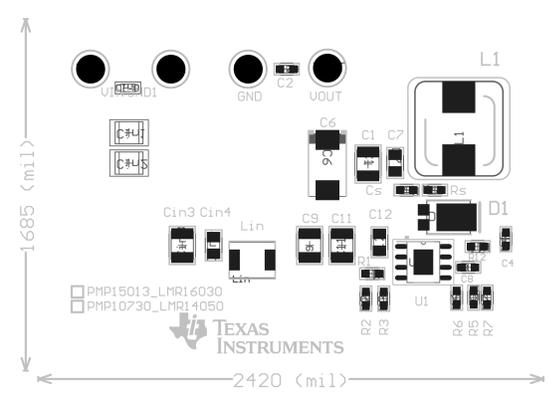
UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS: MICROSECTION: YES

BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER

MANUFACTURER'S ID/LOGO: RAIL METAL SILK

- Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- These assemblies are ESD sensitive, ESD precautions shall be observed.
- These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
ASSEMBLY VARIANT: CISPR 22 Version

| | | | |
|--------------------------|----------------------------------|-------------------|--------------------------------|
| PCB VIEWED FROM TOP SIDE | BOARD #: | REV: B | SUN REV: Not In VersionControl |
| LAYER NAME = | | | |
| PLOT NAME = | GENERATED : 5/30/2016 4:00:48 PM | TEXAS INSTRUMENTS | |

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| | |
|-------------------------|--|
| ENGINEER: Vincent Zhang | LAYOUT BY: Vincent Zhang |
| SCALE: 1.00 | ALTIUM DESIGNER VERSION: .Application_16 |

| Layer Name | Gerber Document | Copper Thickness | Dielectric Height | Dielectric Material | Dielectric Type |
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| Bottom Solder Mask | (.GBS) | | 0.4mil | | Solder Resist |

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MATERIAL:

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 OTHER +/- _____

BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

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OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)

INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz)

DRILLING:

REFERENCE: AS SHOWN NC_DRILL FILES

PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:

SILKSCREEN: TOP BOTTOM

SILKSCREEN COLOR: WHITE OTHER _____

SOLDER RESIST COLOR: GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG) Pb-FREE HASL
 OTHER _____

ARRAY/PANEL: CUT AND TRM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

ANSI IPC-A-600F CLASS -> 1 2 3

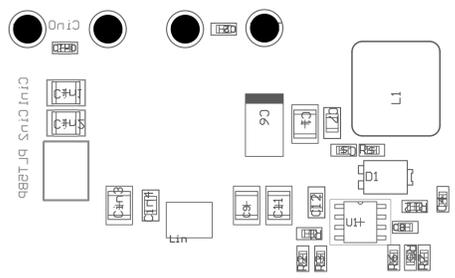
UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS: MICROSECTION: YES

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|--------------------------|----------------------------------|-------------------|--------------------------------|
| PCB VIEWED FROM TOP SIDE | BOARD #: | REV: B | SUN REV: Not In VersionControl |
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| SCALE: 1.00 | ALTIUM DESIGNER VERSION: .Application_16 |

| Layer Name | Gerber Document | Copper Thickness | Dielectric Height | Dielectric Material | Dielectric Type |
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| Bottom Layer | (.GBL) | 2.8mil | | | |
| Bottom Solder Mask | (.GBS) | | 0.4mil | | Solder Resist |

| DESIGN INFORMATION | |
|--------------------------|---|
| BOARD SIZE | (REFER ALSO ARRAY/PANEL PROFILING INFORMATION) |
| | <u>3000MIL</u> X <u>3000MIL</u> |
| Number of Layers : | <u>4</u> |
| MIN. TRACK WIDTH: | <u>8</u> MIL |
| MIN. CLEARANCE: | <u>8</u> MIL |
| MIN. VIA PAD SIZE: | <u>22</u> MIL |
| MINIMUM ANNULAR RING PER | 0.05mm (2MIL) EXTERNAL IPC-D-275 CLASS 2 LEVEL C |
| REGISTRATION TOLERANCES: | METAL +/- <u>5</u> MIL, HOLES +/- <u>3</u> MIL |

MATERIAL:

FR-4 FR-4 High Tg OTHER _____

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 OTHER +/- _____

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INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz)

DRILLING:

REFERENCE: AS SHOWN NC_DRILL FILES

PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:

SILKSCREEN: TOP BOTTOM

SILKSCREEN COLOR: WHITE OTHER _____

SOLDER RESIST COLOR: GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG) Pb-FREE HASL
 OTHER _____

ARRAY/PANEL: CUT AND TRM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

ANSI IPC-A-600F CLASS -> 1 2 3

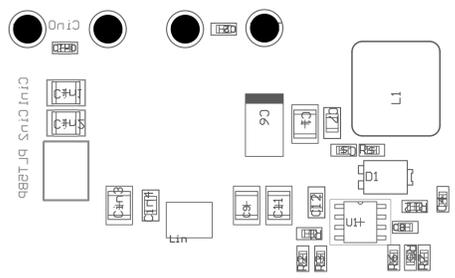
UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS: MICROSECTION: YES

BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER

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| | |
|-------------------------|--|
| ENGINEER: Vincent Zhang | LAYOUT BY: Vincent Zhang |
| SCALE: 1.00 | ALTIUM DESIGNER VERSION: .Application_16 |



| |
|--|
| PROJECT TITLE: PMP15013 |
| DESIGNED FOR: |
| FILE NAME: PMP15013_LMR16030_Update.PcbDoc |

| Layer Name | Gerber Document | Copper Thickness | Dielectric Height | Dielectric Material | Dielectric Type |
|--------------------|-----------------|------------------|-------------------|---------------------|-----------------|
| Top Solder Mask | (.GTS) | | 0.4mil | | Solder Resist |
| Top Layer | (.GTL) | 2.8mil | 19mil | FR-4 | Core |
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MATERIAL:

FR-4 FR-4 High Tg OTHER _____

THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____

TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

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INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz)

DRILLING:

REFERENCE: AS SHOWN NC_DRILL FILES

PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:

SILKSCREEN: TOP BOTTOM

SILKSCREEN COLOR: WHITE OTHER _____

SOLDER RESIST COLOR: GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG) Pb-FREE HASL
 OTHER _____

ARRAY/PANEL: CUT AND TRM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

ANSI IPC-A-600F CLASS -> 1 2 3

UL 94V-0 RoHS OTHER PER ORDER

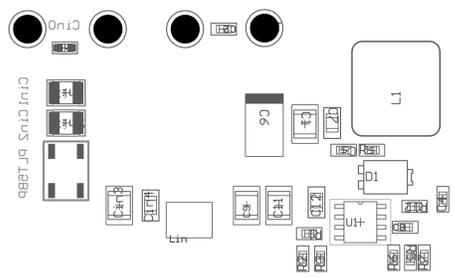
ADDITIONAL REQUIREMENTS:

MICROSECTION: YES

BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER

MANUFACTURER'S ID/LOGO: RAIL METAL SILK

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 ASSEMBLY VARIANT: CISPR 22 Version

| | | | | |
|--------------------------|----------------------------------|-------------------|--------------------------------|--|
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| LAYER NAME = | | | | |
| PLOT NAME = | GENERATED : 5/30/2016 4:00:58 PM | TEXAS INSTRUMENTS | | |
| ENGINEER: Vincent Zhang | | | | LAYOUT BY: Vincent Zhang |
| SCALE: 1.00 | | | | ALTIUM DESIGNER VERSION: .Application_16 |

TEXAS INSTRUMENTS

PROJECT TITLE: PMP15013

DESIGNED FOR:

FILE NAME: PMP15013_LMR16030_Update.PcbDoc

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